

#### **DESCRIPTION**

The IS127 is an optically coupled isolator consisting of an infrared light emitting diodeand a high voltage NPN silicon photo darlington which has an integral baseemitter resistor to optimise switching speed and elevated temperature characteristics in a space efficient Mini Flat package.

### **FEATURES**

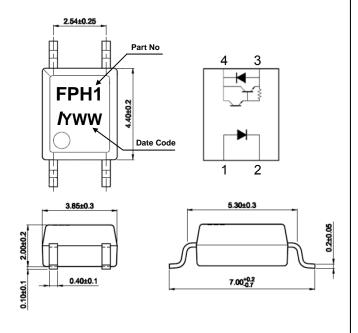
- Low Profile Package
- AC Isolation Voltage 3750V<sub>RMS</sub>
- CTR Minimum 1000%
- High Collector-Emitter Voltage V<sub>CEO</sub> 300V
- Wide Operating Temperature Range -55°C to +110°C
- Lead Free and RoHS Compliant
- UL File E91231 Package Code "FPH1"

#### **APPLICATIONS**

- Computer Terminals
- Industrial System Controllers
- Measuring Instruments
- Signal Transmission between Systems of Different Potentials and Impedances

### **ORDER INFORMATION**

 Available in Tape and Reel with 750 pieces per reel



### **ABSOLUTE MAXIMUM RATINGS**

#### **Input Diode**

Forward Current	50mA
Reverse Voltage	6V
Power dissipation	70mW

#### **Output Transistor**

Collector to Emitter Voltage BV <sub>CEO</sub>	300V
Emitter to Collector Voltage BV <sub>ECO</sub>	0.1V
Collector Current	150mA
Power Dissipation	150mW

#### **Total Package**

Operating Temperature	-55 to +110 °C
Storage Temperature	-55 to +150 °C
Total Power Dissipation	170mW
Lead Soldering Temperature	260°C
(for 10s)	

#### **ISOCOM COMPONENTS 2004 LTD**

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## **ELECTRICAL CHARACTERISTICS** (Ambient Temperature = 25°C unless otherwise specified)

### **INPUT**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Forward Voltage	$V_{\rm F}$	$I_F = 10 \text{mA}$		1.2	1.4	V
Reverse Leakage	$I_R$	$V_R = 4V$			10	μΑ
Terminal Capacitance	$C_{t}$	V = 0V, $f = 1KHz$		30	250	pF

### **OUTPUT**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Collector-Emitter breakdown Voltage	BV <sub>CEO</sub>	$I_C = 0.1 \text{mA}, I_F = 0 \text{mA}$	300			V
Emitter-Collector breakdown Voltage	$\mathrm{BV}_{\mathrm{ECO}}$	$I_E = 10\mu A, I_F = 0mA$	0.1			V
Collector-Emitter Dark Current	$I_{CEO}$	$V_{CE} = 200V, I_F = 0mA$			200	nA

### **COUPLED**

Parameter	Symbol	Test Condition	Min	Тур.	Max	Unit
Current transfer ratio	CTR	$I_F = 1 \text{mA}, V_{CE} = 2V$	1000			%
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$I_F = 20 \text{mA}, I_C = 100 \text{mA}$			1.2	V
Input to Output Isolation Voltage	$V_{\rm ISO}$	See note 1	3750			$V_{RMS}$
Input to Output Isolation Resistance	R <sub>ISO</sub>	V <sub>IO</sub> = 500V See note 1	5x10 <sup>10</sup>			Ω
Output Rise Time	t <sub>r</sub>	$V_{CE} = 2V$ , $Ic = 20mA$ , $R_L = 100\Omega$		100	300	μs
Output Fall Time	t <sub>f</sub>	$V_{CE} = 2V$ , $Ic = 20mA$ , $R_L = 100\Omega$		20	100	μs

Note 1: Measure with input leads shorted together and output leads shorted together.



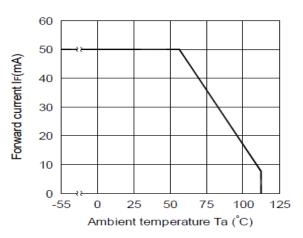


Fig 1 Forward Current vs  $T_A$ 

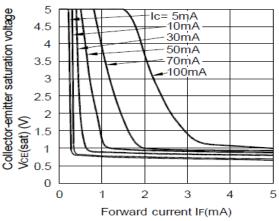


Fig 3 Collector-emitter Saturation Voltage vs Forward Current

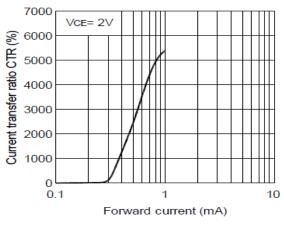


Fig 5 Current Transfer Ratio vs Forward Current

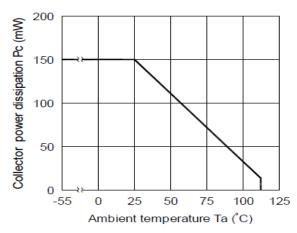


Fig 2 Collector Power Dissipation vs TA

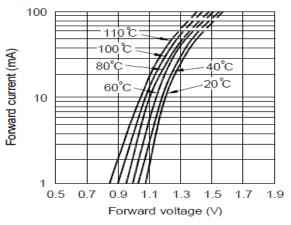


Fig 4 Forward Current vs Forward Voltage

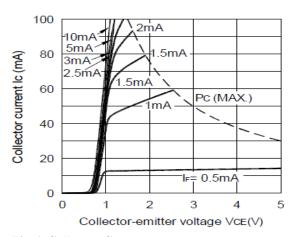


Fig 6 Collector Current vs Collector-Emitter Voltage



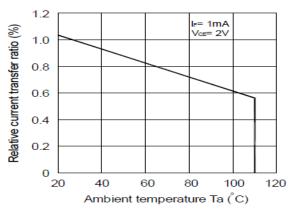


Fig 7 Relative CTR vs T<sub>A</sub>

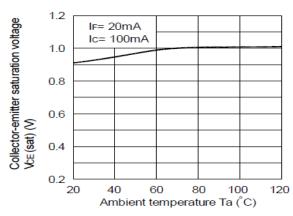


Fig 8 Collector-Emitter Saturation Voltage vs T<sub>A</sub>

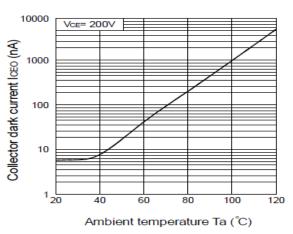


Fig 9 Collector Dark Current vs  $T_A$ 

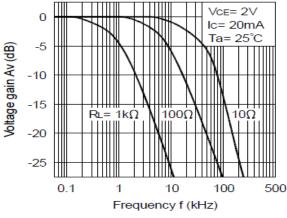


Fig 10 Frequency Response

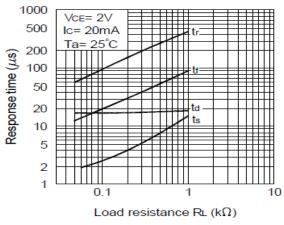
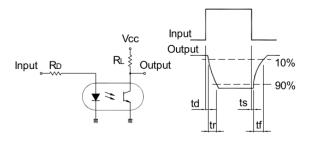


Fig 11 Response Time vs Load Resistance



**Response Time Test Circuit** 



### STANDARD PACKING QUANTITY

IS127				
After PN	PN	Description	Packing quantity	
None	IS127	Surface Mount Tape & Reel	750 pcs per reel	

### **DEVICE MARKING**



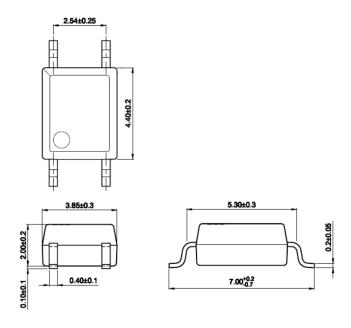
FPH1 denotes Device Part Number where "#" is internal control number

I denotes Isocom

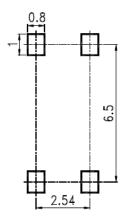
Y denotes 1 digit Year code WW denotes 2 digit Week code



## **PACKAGE DIMENSIONS (mm)**



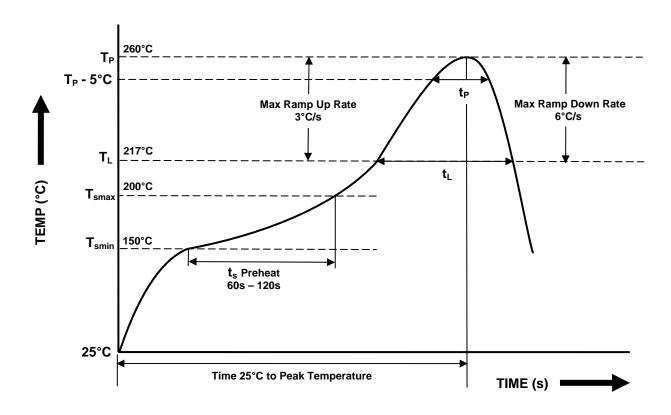
## **RECOMMENDED SOLDER PAD LAYOUT (mm)**



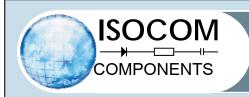


### IR REFLOW SOLDERING TEMPERATURE PROFILE

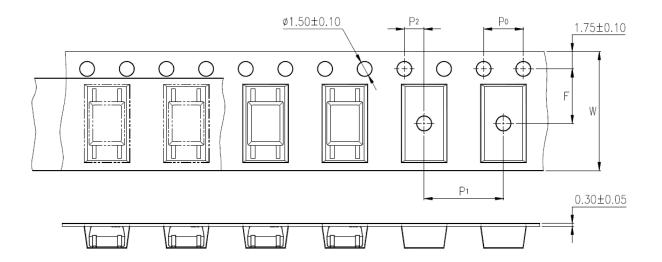
(One Time Reflow Soldering is Recommended)



Profile Details	Conditions
$ \begin{array}{l} \textbf{Preheat} \\ \textbf{- Min Temperature } (T_{SMIN}) \\ \textbf{- Max Temperature } (T_{SMAX}) \\ \textbf{- Time } T_{SMIN} \text{ to } T_{SMAX} \left(t_s\right) \end{array} $	150°C 200°C 60s - 120s
$\begin{tabular}{lll} \textbf{Soldering Zone} \\ - & \mbox{Peak Temperature } (T_P) \\ - & \mbox{Liquidous Temperature } (T_L) \\ - & \mbox{Time within } 5^{\circ}\mbox{C of Actual Peak Temperature } (T_P - 5^{\circ}\mbox{C}) \\ - & \mbox{Time maintained above } T_L \ (t_L) \\ - & \mbox{Ramp Up Rate } (T_L \ \mbox{to } T_P) \\ - & \mbox{Ramp Down Rate } (T_P \ \mbox{to } T_L) \\ \end{tabular}$	260°C 217°C 20s 60s 3°C/s max 3 - 6°C/s
Average Ramp Up Rate (T <sub>smax</sub> to T <sub>P</sub> )	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



## TAPE AND REEL PACKAGING (mm)



Description	Symbol	Dimensions in mm (inches)
Tape wide	W	12 ± 0.3 ( .47 )
Pitch of sprocket holes	P <sub>0</sub>	4 ± 0.1 ( .15 )
Distance of compartment	F	$5.5 \pm 0.1  (.217)$
Distance of compartment	$\mathbf{P}_2$	2 ± 0.1 ( .079 )
Distance of compartment to compartment	P1	8 ± 0.1 ( .315 )



### **NOTES:**

- Isocom is continually improving the quality, reliability, function or design and Isocom reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/application where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc., please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales for advice.
- The contents described herein are subject to change without prior notice.
- Do not immerse device body in solder paste.